

Fig. 1

FIG. 1

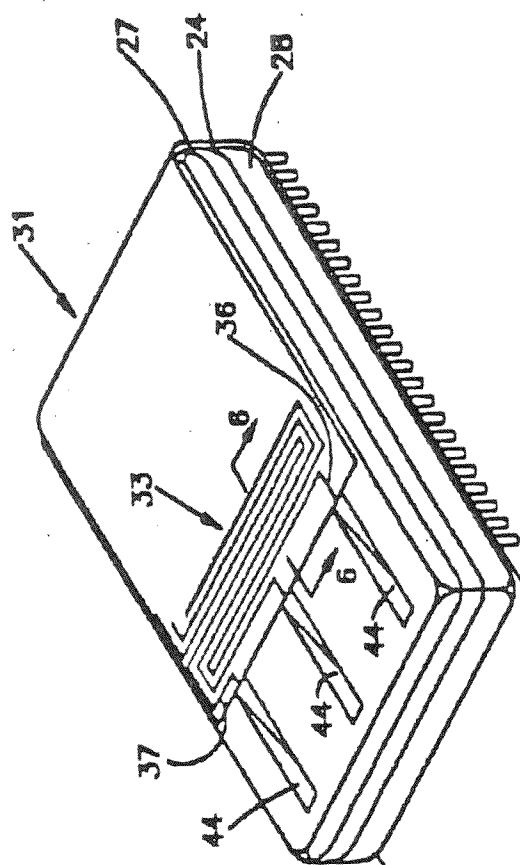


Fig. 2

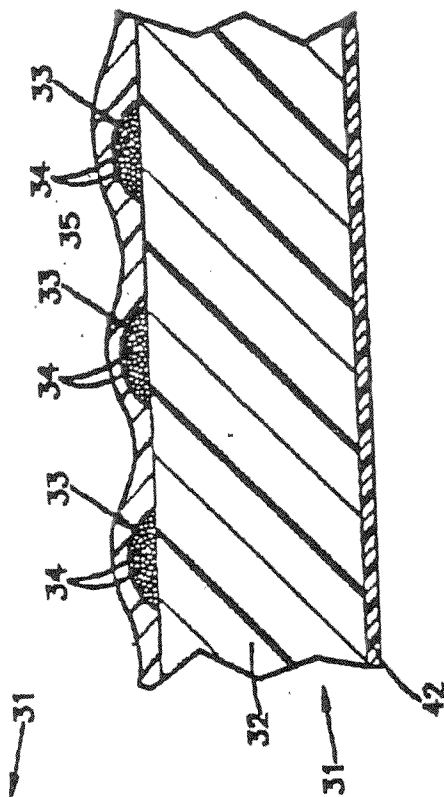


Fig. 3

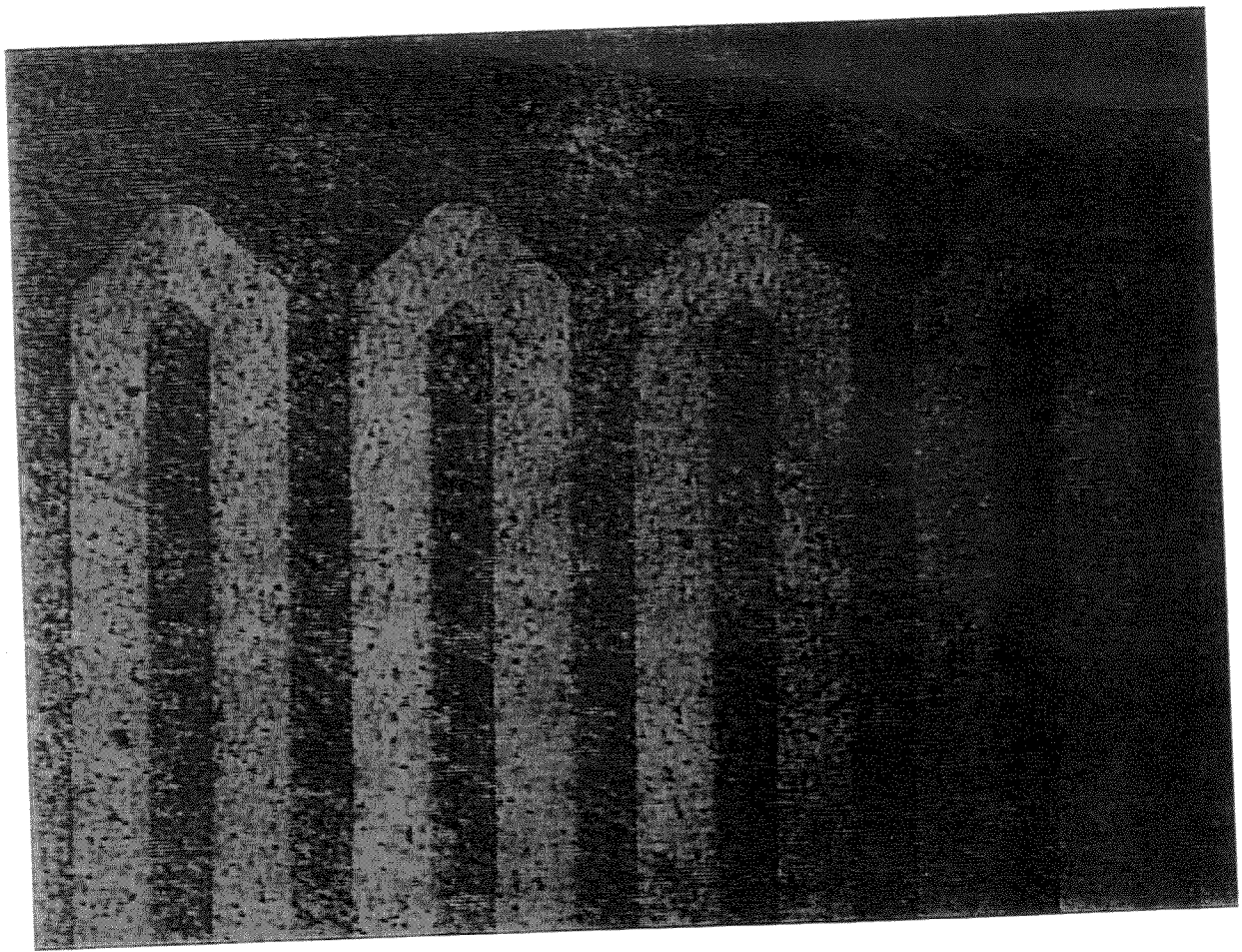


Fig. 4



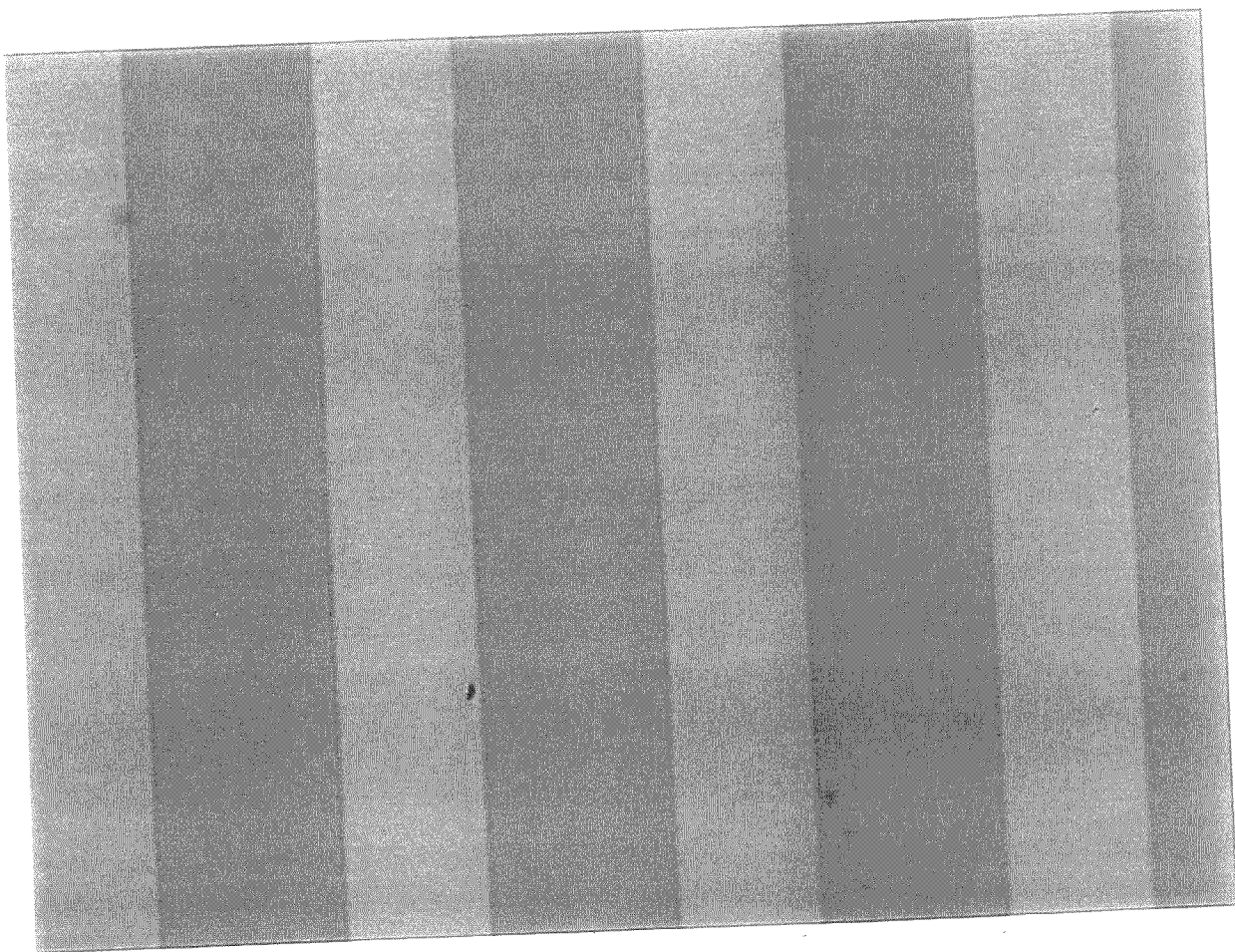


Fig. 6



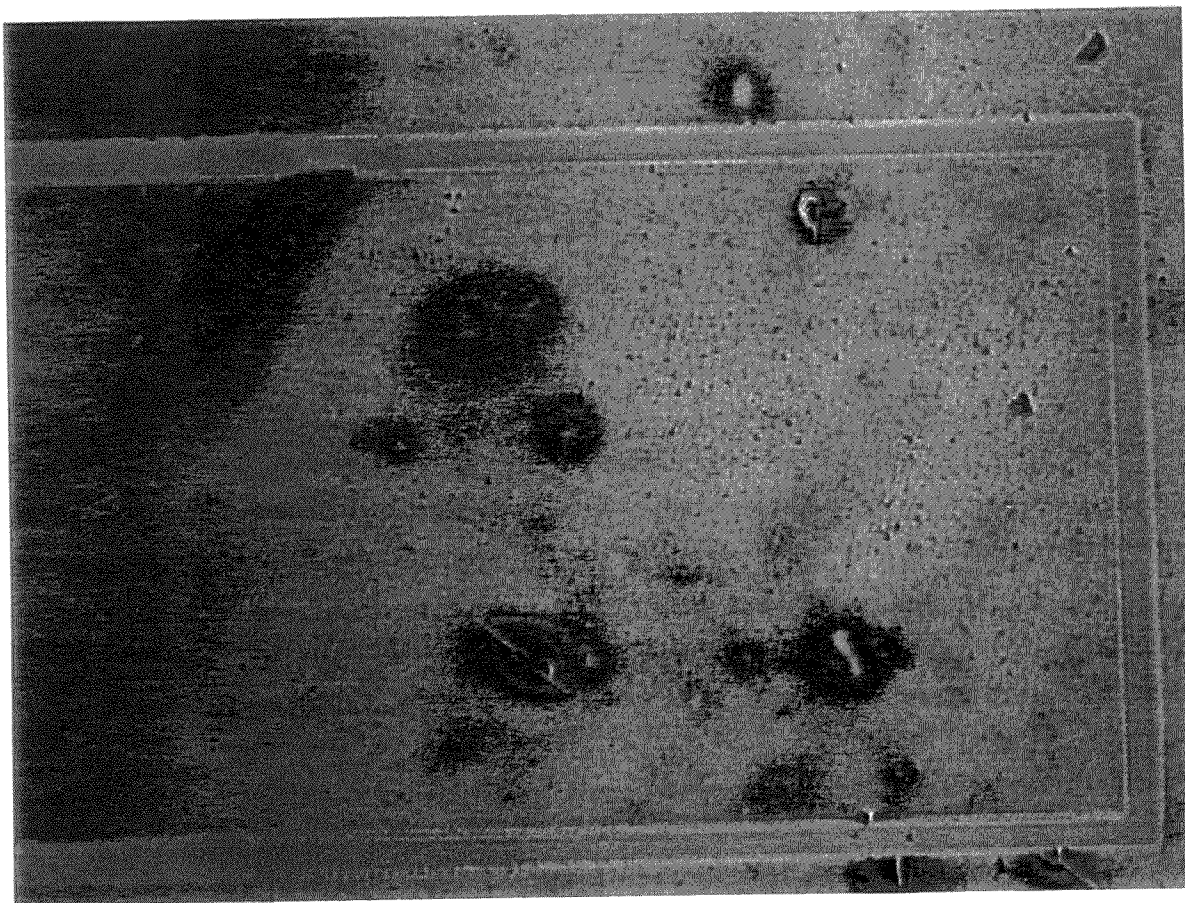


Fig. 8

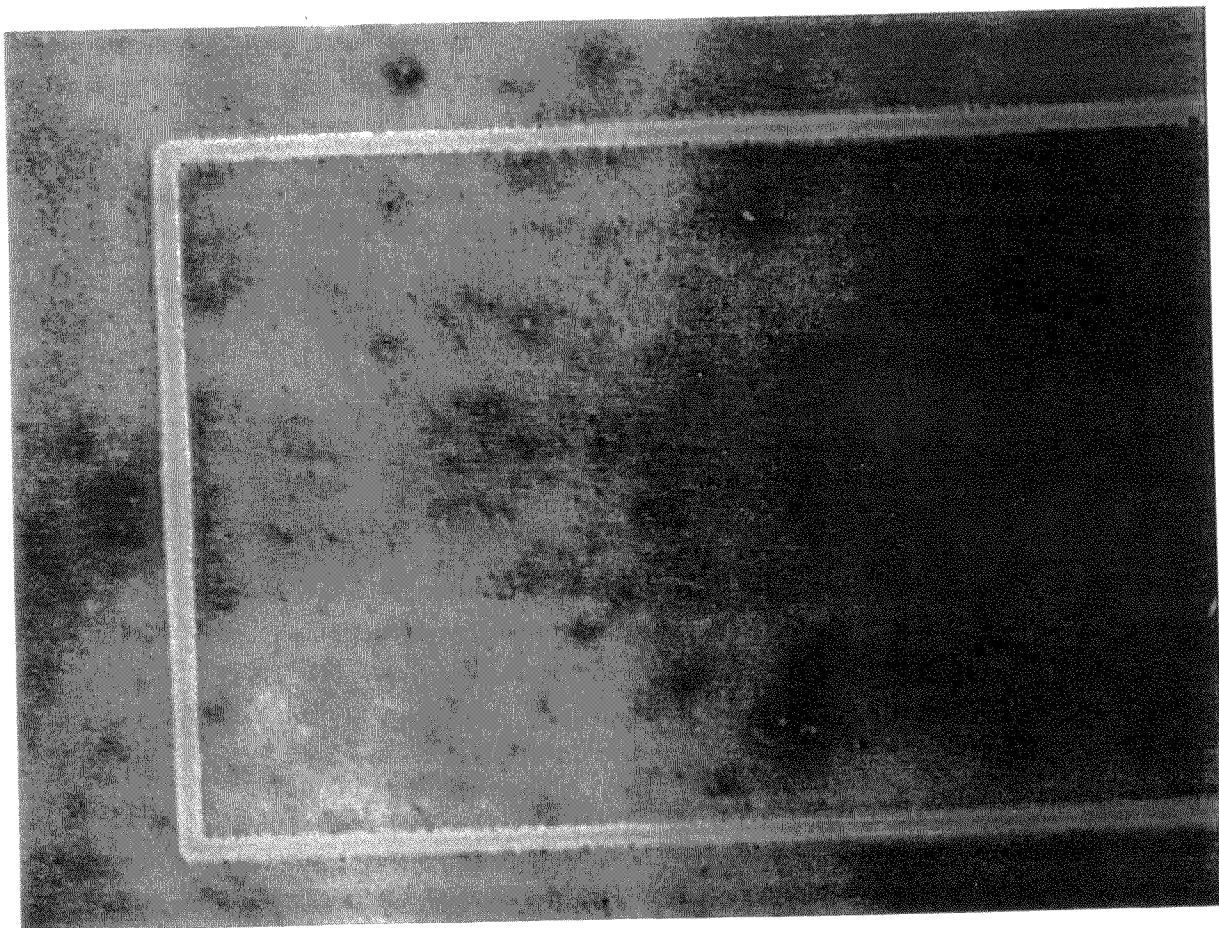


Fig. 9





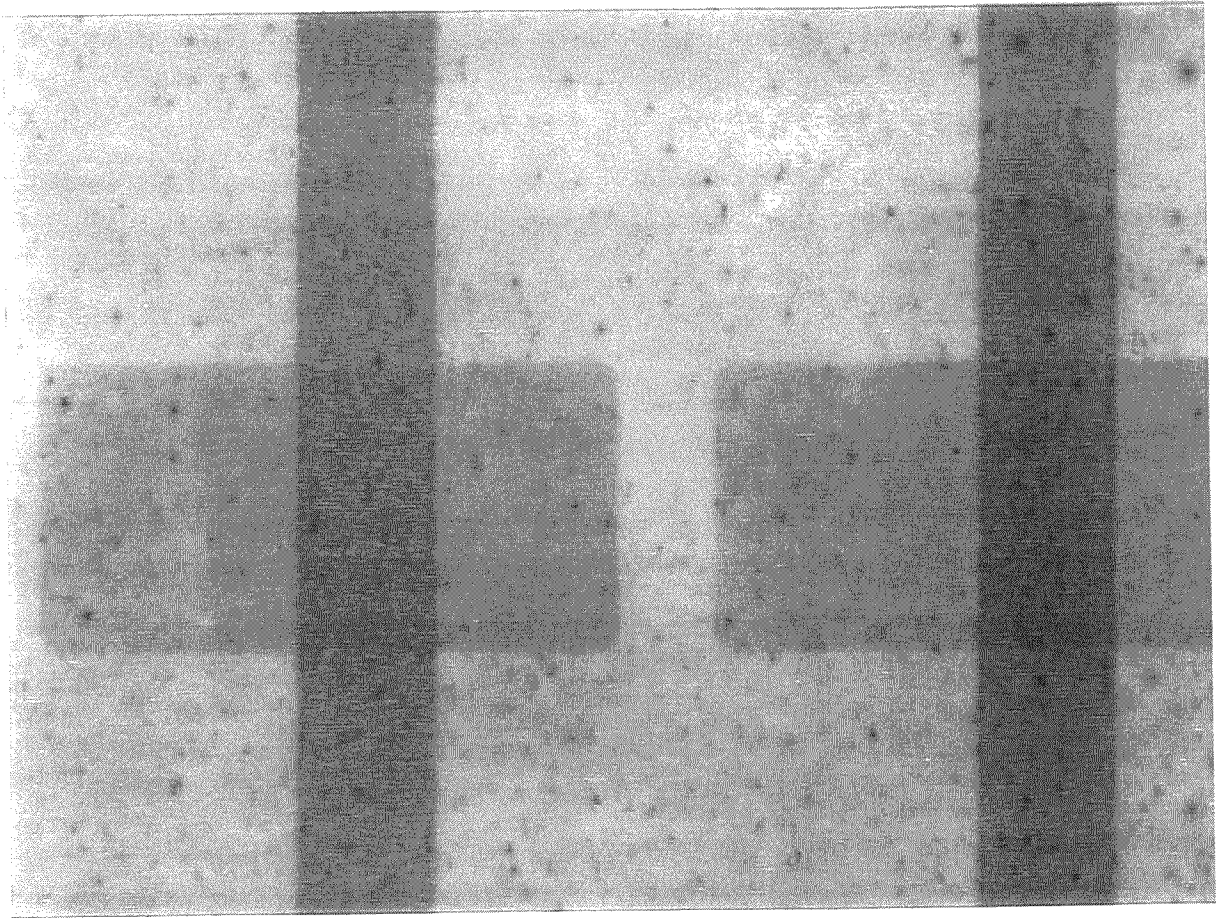


Fig. 12

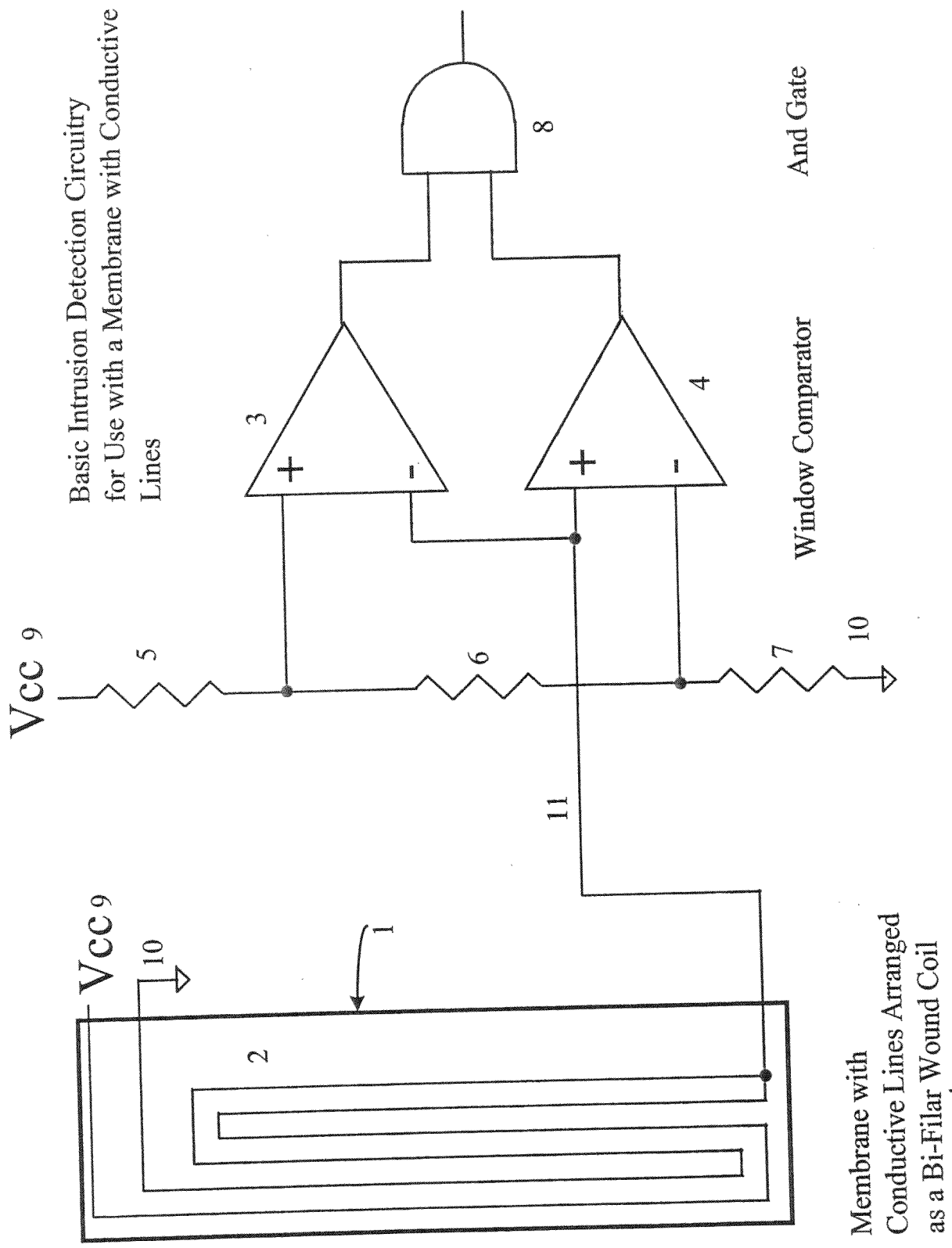


Fig. 13

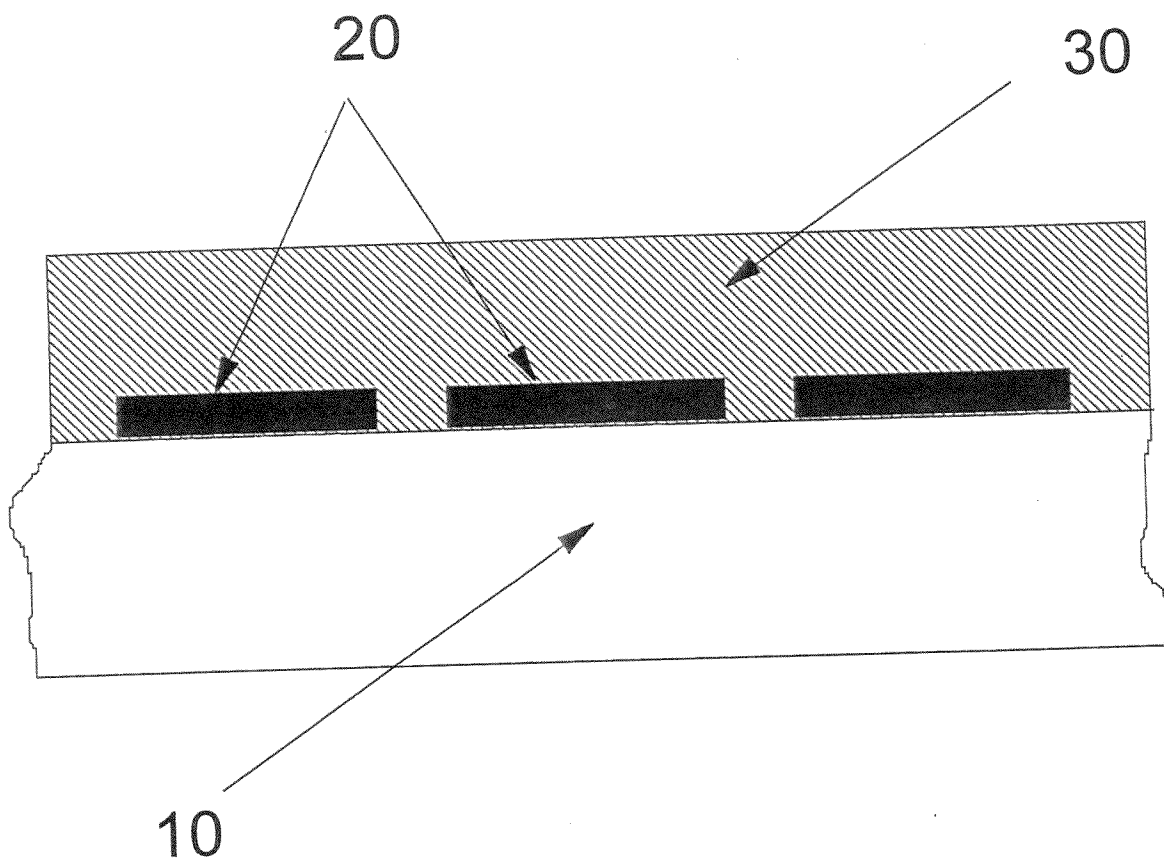


Fig. 14

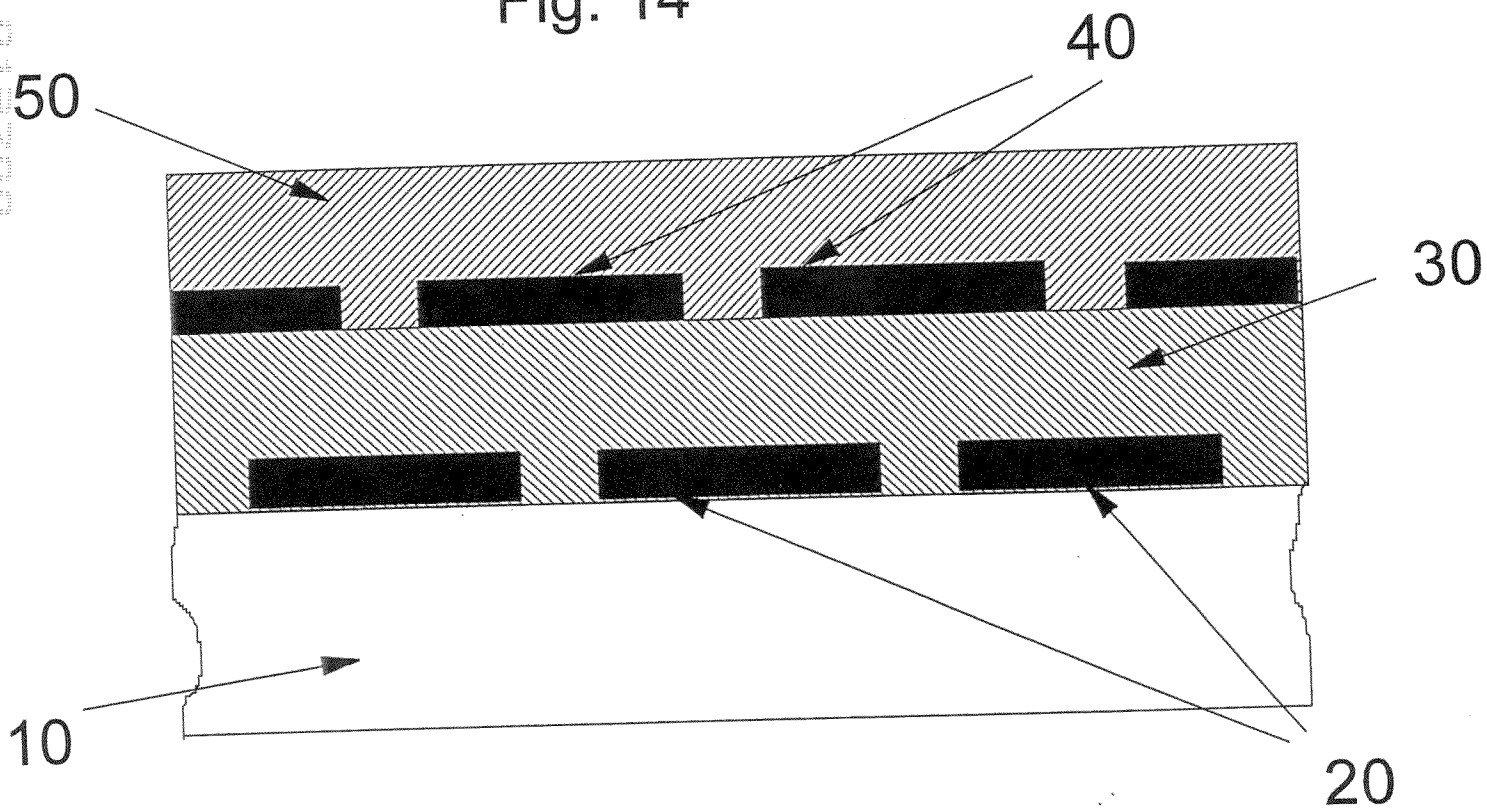


Fig. 15

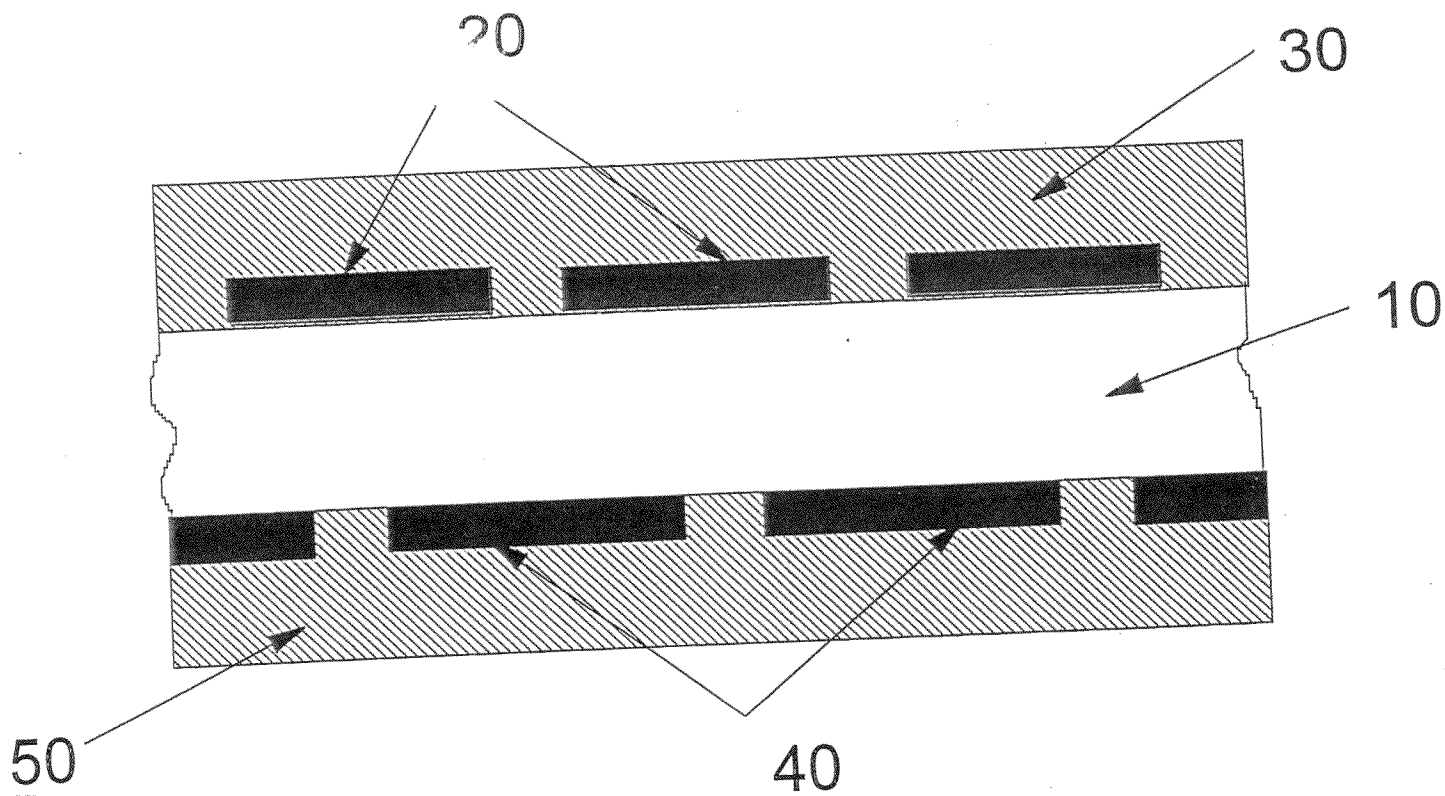


Fig. 16

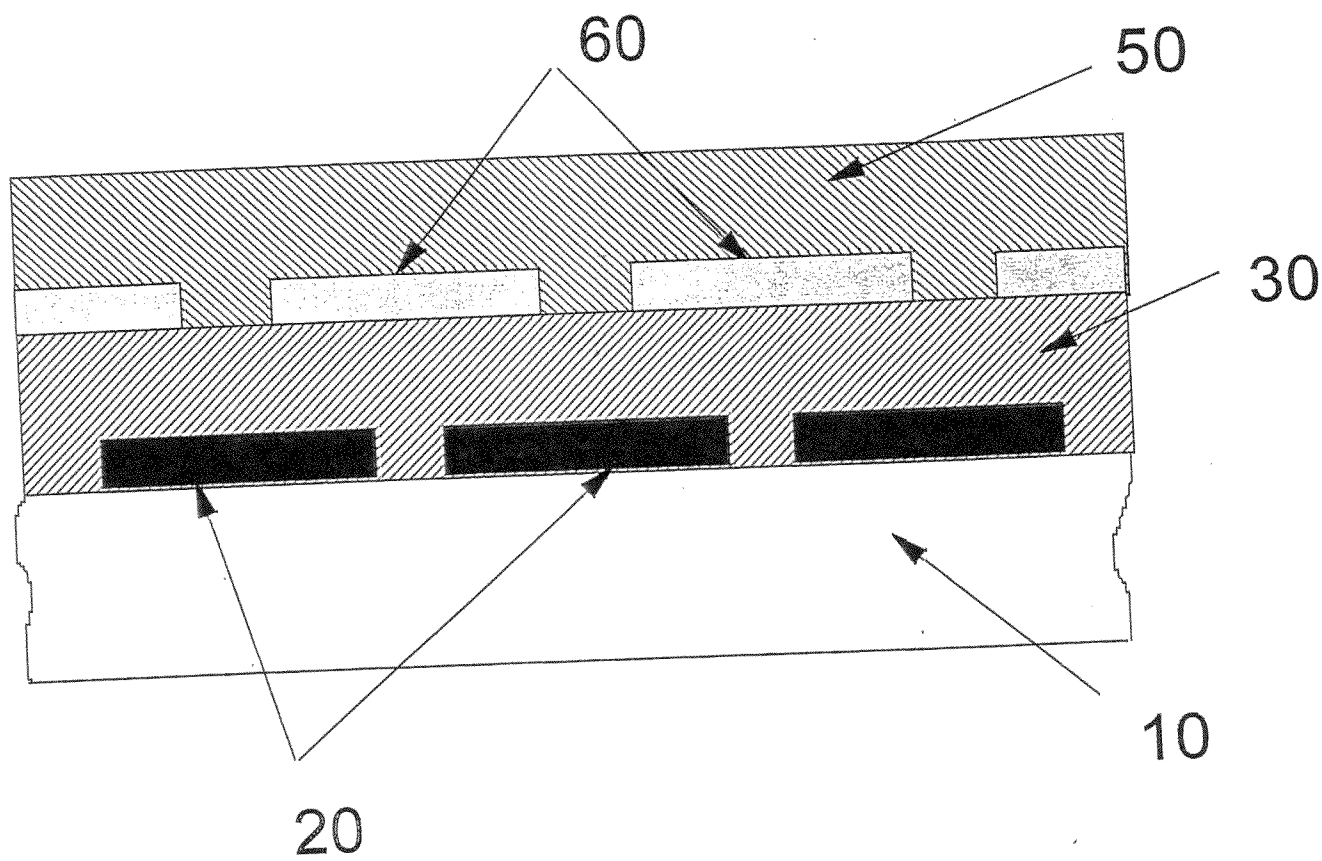


Fig. 17

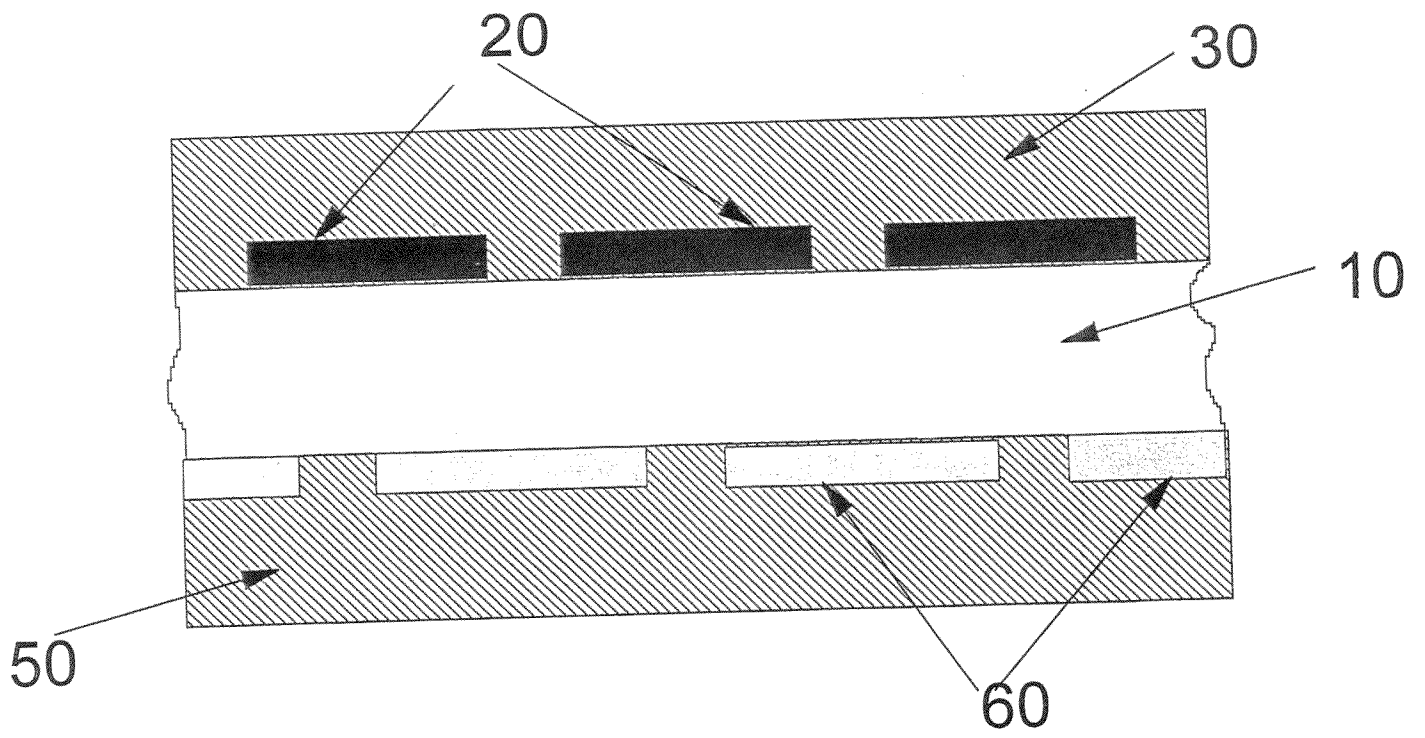


Fig. 18

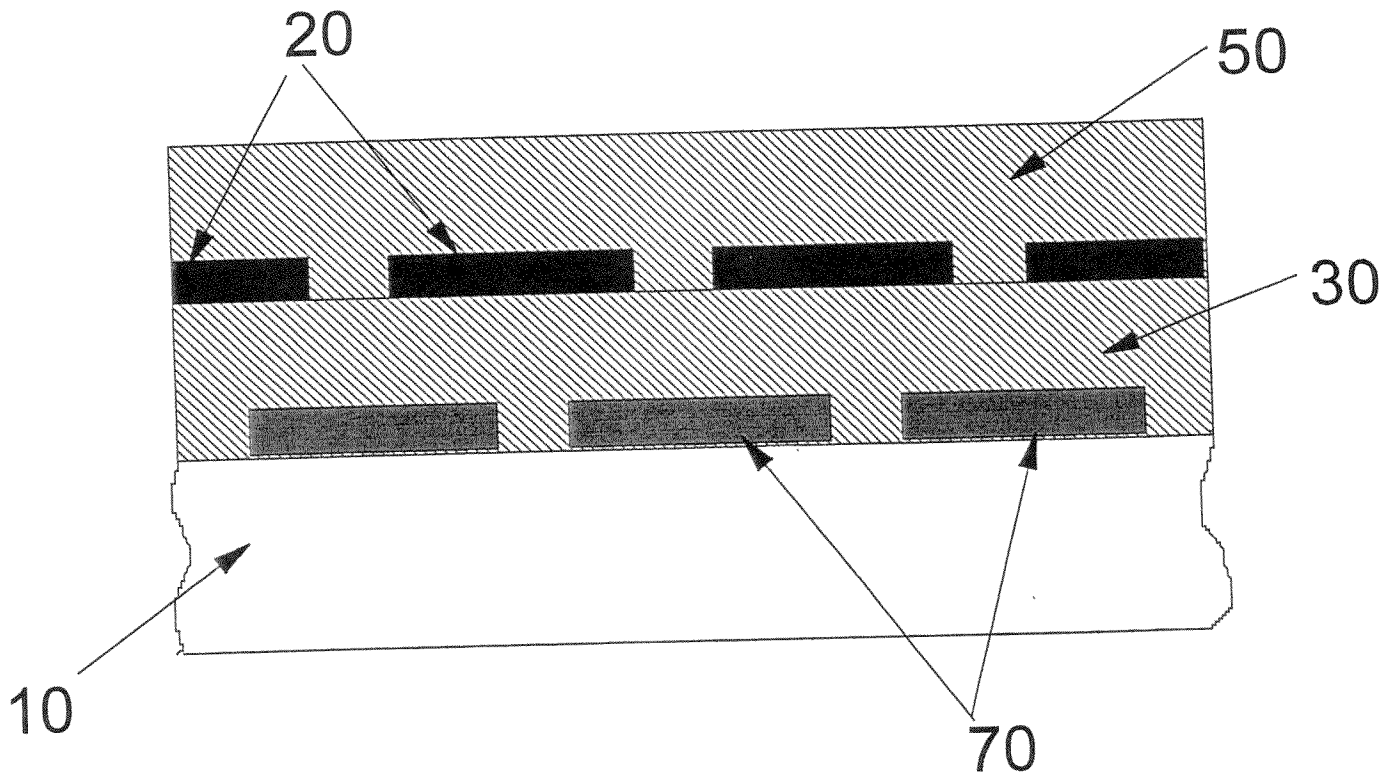


Fig. 19

FIG. 20 is a cross-sectional view of a device 10, showing a substrate 20 with a top layer 30 and a bottom layer 50. The substrate 20 contains a series of rectangular openings 70. The top layer 30 and bottom layer 50 are formed of a material different from the substrate 20. The openings 70 are formed in the substrate 20 and are filled with a material different from the substrate 20. The top layer 30 and bottom layer 50 are formed of a material different from the substrate 20. The openings 70 are formed in the substrate 20 and are filled with a material different from the substrate 20.

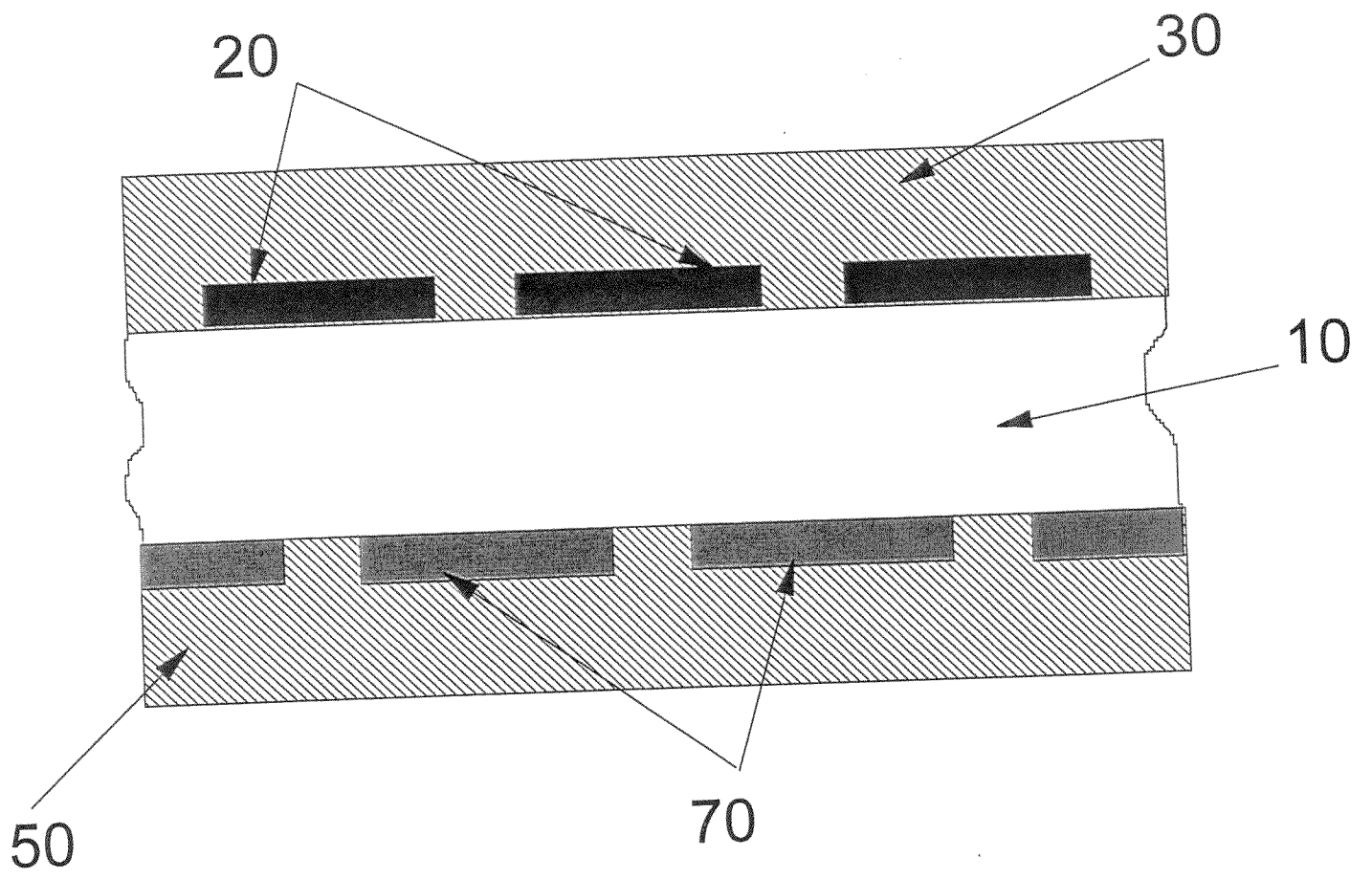


Fig. 20